

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

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Declarations Autorisiert durch:

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Materialien und Stoffe

Verwendung/Andordnung	Materialgruppe	% w/w des Materials im Artikel	Substances in the material	CAS Number	% w/w des Stoffs im Artikel
Chip (die)	Other inorganic materials	0.95%	Gold	7440-57-5	0.06%
			BETA-ALUMINUM OXIDE	1344-28-1	0.55%
			Nickel	7440-02-0	1.72%
			Silicon Dioxide	7631-86-9	5.7%
			Silicon	7440-21-3	91.97%
Die attach	Lead and Lead alloys	2.55%	Silver	7440-22-4	2.5%
			Tin	7440-31-5	5%
			Lead	7439-92-1	92.5%
Encapsulation	EP (Epoxy resin)	15.66%	Carbon black	1333-86-4	0.3%
			Antimony oxide	1309-64-4	0.8%
			Phenol, 4,4'-(1-methylethylidene)bis[2,6-dibromo-, polymer with (chloromethyl)oxirane	40039-93-8	0.99%
			resin	9003-35-4	5%
			Epoxy resin ERL-2795	25068-38-6	27.61%
Leadfinish	Tin plating	1.36%	Fused Silica	60676-86-0	65.3%
			Tin	7440-31-5	100%

Verwendung/Andordnung	Materialgruppe	% w/w des Materials im Artikel	Substances in the material	CAS Number	% w/w des Stoffs im Artikel
Leadframe	Copper (e.g. copper amounts in cable harnesses)	79.48%	Phosphorus	7723-14-0	0.02%
			Iron	7439-89-6	0.1%
			Copper	7440-50-8	99.88%

Beigefügte Artikelliste

Artikelnummer	Artikelbezeichnung	Artikelmasse	Artikelmasse UoM
DO-218AB	Diode SMD	2.9	g

No need to provide safe use information beyond the identification of the Candidate List substance